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DATE MAILED: 05/16/2003

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/054,124	01/22/2002	Jeffrey Alan Miks	AMKOR-003A	6418	
7663 7	590 05/16/2003			<u>.</u>	
STETINA BRUNDA GARRED & BRUCKER 75 ENTERPRISE, SUITE 250 ALISO VIEJO, CA 92656			EXAM	EXAMINER	
			WILLIAMS, AI	WILLIAMS, ALEXANDER O	
			ART UNIT	PAPER NUMBER	
			2826		

Please find below and/or attached an Office communication concerning this application or proceeding.

				Man			
•		Application No.	Applicant(s)				
Office Action Summary		10/054,124	MIKS, JEFFREY	ALAN			
		Examiner	Art Unit				
		Alexander O Williams	2826				
Period fo	The MAILING DATE of this communication ap	pears on the cover sheet	with the correspondence a	adress			
	ORTENED STATUTORY PERIOD FOR REPL	Y IS SET TO EXPIRE 3	MONTH(S) FROM				
THE N - Exter after - If the - If NO - Failu	MAILING DATE OF THIS COMMUNICATION. Insions of time may be available under the provisions of 37 CFR 1. SIX (6) MONTHS from the mailing date of this communication. Inside the period for reply specified above is less than thirty (30) days, a reply period for reply is specified above, the maximum statutory period re to reply within the set or extended period for reply will, by staturely received by the Office later than three months after the mailing and patent term adjustment. See 37 CFR 1.704(b).	.136(a). In no event, however, may ply within the statutory minimum of the will apply and will expire SIX (6) Metal cause the application to become	a reply be timely filed hirty (30) days will be considered tim ONTHS from the mailing date of this ABANDONED (35 U.S.C. § 133).	ely. communication.			
1) 🖾	Responsive to communication(s) filed on 27	February 2003 .					
2a)□	•	his action is non-final.					
3)	with the ments is						
-	ion of Claims						
	Claim(s) 1-7 and 17-26 is/are pending in the						
	4a) Of the above claim(s) is/are withdrawn from consideration.						
5)	Claim(s) is/are allowed.						
=	Claim(s) <u>1-7 and 17-26</u> is/are rejected.						
	Claim(s) is/are objected to.						
	Claim(s) are subject to restriction and	or election requirement.					
• -	tion Papers	oor					
9) 🗀	The specification is objected to by the Examir	noted or hill objected to h	v the Examiner				
10)	The drawing(s) filed on is/are: a) accomplicant may not request that any objection to	the drawing(s) be held in ab	evance. See 37 CFR 1.85(a	a).			
441	The proposed drawing correction filed on	is: a) ☐ approved b) ☐	disapproved by the Exam	niner.			
11)	If approved, corrected drawings are required in		- •				
121□	12) The oath or declaration is objected to by the Examiner.						
	under 35 U.S.C. §§ 119 and 120						
		ign priority under 35 U.S.	C. § 119(a)-(d) or (f).				
	3) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of:						
a,	1. Certified copies of the priority documents have been received.						
	2. Certified copies of the priority documents have been received in Application No						
*	3. Copies of the certified copies of the prapplication from the International See the attached detailed Office action for a li	riority documents have be Bureau (PCT Rule 17.2(a	een received in this Natior))).	nal Stage			
14)	Acknowledgment is made of a claim for dome	estic priority under 35 U.S	.C. § 119(e) (to a provisio	nal application).			
	a) The translation of the foreign language Acknowledgment is made of a claim for dome	provisional application ha	s been received.				
Attachme							
2) Not	tice of References Cited (PTO-892) tice of Draftsperson's Patent Drawing Review (PTO-948) ormation Disclosure Statement(s) (PTO-1449) Paper No(s	5) Notice	iew Summary (PTO-413) Paper e of Informal Patent Application :				
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Serial Number: 10/054124 Attorney's Docket #: AMKOR.003A

Filing Date: 1/22/02;

Applicant: Miks

Examiner: Alexander Williams

Applicant's Amendment (claims 1 to 7 and 17 to 26) in Paper # 6, filed 2/27/03, has been acknowledged.

Applicant's Declaration in Paper # 7, filed 2/27/03, has been acknowledged.

Claims 8 to 16 have been canceled.

The following is a quotation of the appropriate paragraphs of 35 U.S.C. § 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- (e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains.

Patentability shall not be negatived by the manner in which the invention was made.

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Claims 1 to 7 and 17 to 26 are rejected under 35 U.S.C. § 102(b) as being anticipated by (Japan Patent # 10-22447).

For example, in claim 1 and similar claims 17 and 28, Japan Patent (figures 1 to 9) specifically figures 8 and 9 show a semiconductor package comprising: a chip mounting pad 23,4 having a peripheral edge 21; a semiconductor chip 20 attached to the chip mounting pad; a plurality of leads 6 each lead including an inner end and an opposing distal end, each inner end being disposed adjacent the peripheral edge in spaced relation thereto and vertically downset with respect to each respective distal end; and at least one isolated ring structure 7,8 disposed along the peripheral edge between the peripheral edge and the inner end of the leads in spaced relation thereto, the ring structure being electrically connected (by 12 and 15) to the semiconductor chip and the inner end of at least one of the leads.

Claims 1 to 7 and 17 to 26 are rejected under 35 U.S.C. § 102(e) as being anticipated by Combs et al. (U.S. Patent # 6,285,075 B1).

For example, in claim 1 and similar claims 17 and 28, Combs et al. (figures 1 to 6) specifically figure 1 show a semiconductor package comprising: a chip mounting pad having a peripheral edge; a semiconductor chip 102 attached to the chip mounting pad; a plurality of leads 109 each lead including an inner end and an opposing distal end, each inner end being disposed adjacent the peripheral edge in spaced relation thereto and vertically downset with respect to each respective distal end; and at least one isolated ring structure 103 disposed along the peripheral edge between the peripheral edge and the inner end of the leads in spaced relation thereto, the ring structure being electrically connected (by 110) to the semiconductor chip and the inner end of at least one of the leads.

Claims 1-7 and 17-26 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gow, 3rd et al. (U.S. Patent # 5,168,368) in view of Casto et al. (U.S. Patent # 5,172,214).

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For example, in claim 1 and similar claims 17 and 28, Gow, 3rd et al. (figures 1 to 4) specifically figure 1 show a semiconductor package 12 comprising: a chip mounting pad 13 having a peripheral edge; a semiconductor chip 10 attached to the chip mounting pad; a plurality of leads 18 each lead including an inner end 18a-n and an opposing distal end, each inner end being disposed adjacent the peripheral edge in spaced relation thereto; and at least one isolated ring structure 24 disposed along the peripheral edge between the peripheral edge and the inner end of the leads in spaced relation thereto, the ring structure being electrically connected (by 20a and 28a) to the semiconductor chip and the inner end of at least one of the leads. Gow, 3rd et al. fail to explicitly show the plurality of leads vertically downset with respect to each respective distal end. However, it is inherit in the device package of Gow, 3rd et al. that some type of electrical connection to an external source for the chip to function as intended. The type of outer leads can be the designer's choice to connect to an external connection.

Casto is cited for showing a leadless semiconductor device. Specifically, Casto (figure 1) discloses a semiconductor package 60 a semiconductor package 12 comprising: a chip mounting pad 65 having a peripheral edge; a semiconductor chip 64 attached to the chip mounting pad; a plurality of leads (63 on the left side of the die) each lead including an inner end 66 and an opposing distal end 68, each inner end being disposed adjacent the peripheral edge in spaced relation thereto; the plurality of leads vertically downset with respect to each respective distal end for the purpose of reducing package size.

Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to use Casto's leads to modify Gow, 3rd et al.'s leads for the purpose of reducing package size.

Response

Applicant's arguments filed 2/27/03 have been fully considered, but are moot in view of the new grounds of rejections detailed above.

The listed references are cited as of interest to this application, but not applied at this time.

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Field of Search	Date
U.S. Class and subclass: 257/666,669-672,674,676,690-693,696,698,784,786,787	11/13/02 5/15/03
Other Documentation: foreign patents and literature in 257/666,669- 672,674,676,690-693,696,698,784,786,787	11/13/02 5/15/03
Electronic data base(s): U.S. Patents EAST	11/13/02 5/15/03

Papers related to this application may be submitted to Technology Center 2800 by facsimile transmission. Papers should be faxed to Technology Center 2800 via the Technology Center 2800 Fax center located in Crystal Plaza 4-5B15. The faxing of such papers must conform with the notice published in the Official Gazette, 1096 OG 30 (November 15, 1989). The Technology Center 2800 Fax Center number is (703) 308-7722 or 24. Only Papers related to Technology Center 2800 APPLICATIONS SHOULD BE FAXED to the GROUP 2800 FAX CENTER.

Any inquiry concerning this communication or any earlier communication from the examiner should be directed to *Examiner Alexander Williams* whose telephone number is **(703) 308-4863**.

Any inquiry of a general nature or relating to the status of this application should be directed to the *Technology Center 2800 receptionist* whose telephone number is (703) 308-0956.

5/15/03

Primary Examiner
Alexander O. Williams